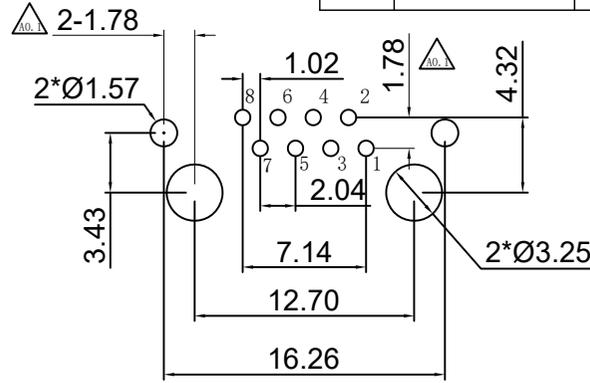
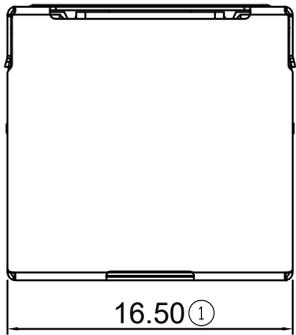


# GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A1			Modify Current Rating => 2A	2025/08/01	Vince
A1.1			Modify Electrical	2025/08/11	Vince
A2			Modify Operating temperature 95° => 100°	2025/08/25	Vince

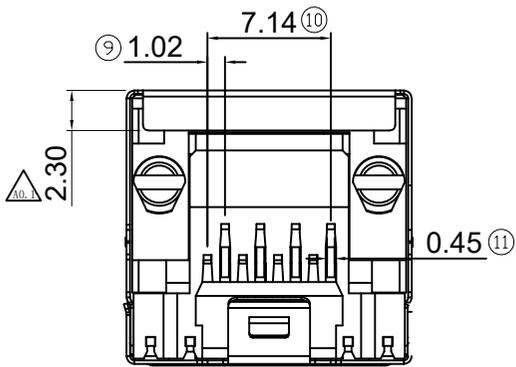
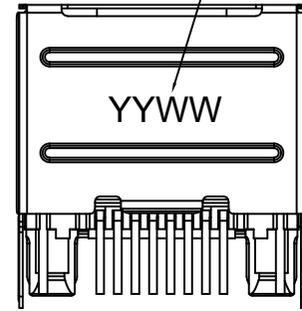
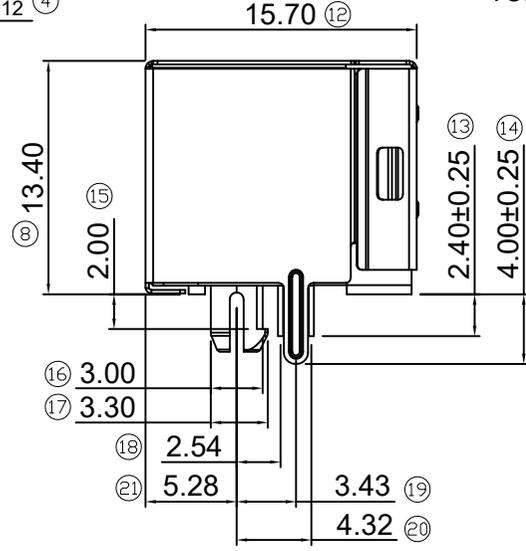
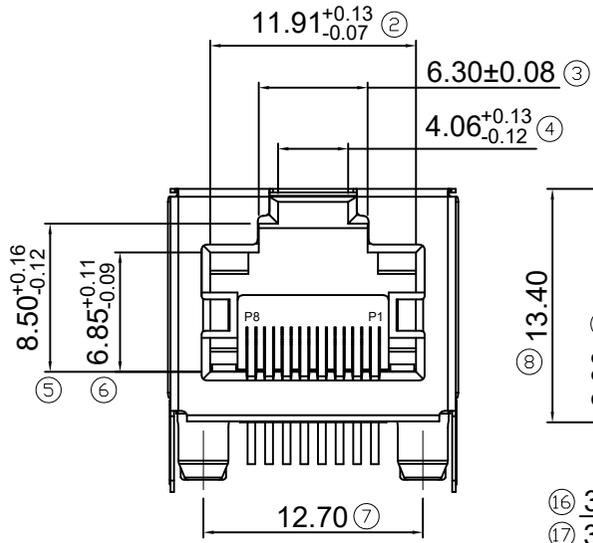


**NOTES:**

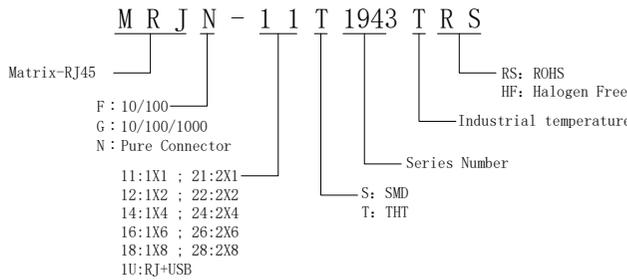
- MATERIALS:**  
HOUSING: PBT , BLACK (UL94V-0).  
CONTACTS: PHOSPHOR BRONZE T=0.30mm.  
SHIELD: C2680,T=0.20mm
- FINISH:**  
CONTACT: 50U" NICKE LUNDERPLAT ON ALL AREA.  
100U"MIN. TIN ON SOLDER TAILS.  
6U" GOLD PLATED ON CONTACT AREA.  
SHIELD:COPPER ALLOY PLATED WITH NICKEL.
- OPERATING TEMPERATURE :** -40°C ~ +100°C.
- STORAGE TEMPERATURE:** -40°C ~ +85°C.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.**
- THIS PRODUCT IS A WAVE-SOLDERING SOLDERING PROCESS.**
- ELECTRICAL:**  
7-1 VOLTAGE RATING: 125 VAC RMS  
7-2 CURRENT RATING PER PIN: 2 AMP.  
7-3 CONTACT RESISTANCE: 40mΩ MAX.  
7-4 INSULATION RESISTANCE: 1000MΩMIN. AT 500V DC.  
7-5 DIELECTRIC STRENGTH: 1000 VAC 50Hz 1MINUTE.
- PACKING SPEC**  
8-1 ESD LEVEL: 1C (The Product Itself Has No Static Electricity Requirement Except LED).  
8-2 HALOGEN FREE: NO  
8-3 LEAD-FREE: METTS LEAD-FREE.  
8-4 MSL LEVEL: LEVEL 2 (1 Year).  
8-5 PACKING: BLISTER PACK.

PCB LAYOUT TOLERANCE:±0.05mm  
TOP VIEW

鑄雕周期



MATRIX PART NO :



<b>Matrix Electronics Co.,Ltd</b>			
<b>TOLERANCE:</b> X:X ±0.38 X:XX ±0.25 X:XXX ±0.13 ANGLE: ±3°	<b>DESIGN BY :</b> Vince Chen	<b>DATE :</b> 2025/08/25	<b>PART NAME:</b> RJ45 1X1 TAB UP
 <b>UNIT: mm [inch]</b> <b>SCALE:1:1 SIZE:A4</b>	<b>CHECKED BY:</b> Hanson Huang	<b>DATE :</b> 2025/08/25	<b>PART NO.</b> MRJN-11T1943TRS
	<b>APPROVED BY1:</b> Richard Hsieh	<b>DATE :</b> 2025/08/25	<b>MOLD NO.</b> NA
	<b>APPROVED BY2:</b> Richard Hsieh	<b>DATE :</b> 2025/08/25	<b>DRAW NO.</b> SHEET NO. 1 OF 2